NICHING

		Ultra High Thermal Application				
Parameter	Test/Measure	DN-1206QB	DN-1206CR1	DN-1208L	DN-1301B	DN-1301C
Curing Temp	degC	200	200	200	175	175
Viscosity @25deg.C	E-viscometer@5rpm	11,000	10,800	23,000	13,000	10,800
Thixotropic Index @25deg.C	0.5rpm/5rpm	5.5	6.1	2.8	5.5	6.1
Volume Resistance	Ohm.cm	$5.5*10^{-6}$	$9.0*10^{-6}$	$4.0*10^{-6}$	$2.5*10^{-6}$	$9.0*10^{-6}$
Thermal Conductivity	W/mk	140	150	200	130	130
Die Shear Strength @25 Deg.C with 2*2 mm Ag BSM Die	On Ag/Cu LF (MPa)	30	32	40	32	32
	On Cu PCB (MPa)	25	32	10	25	27
Die Shear Strength @260 Deg.C 2*2 mm Ag BSM Die	On Ag/Cu LF (MPa)	19	17	100	19	16
	On Cu PCB (MPa)	10	10	10	12	10
Storage Modulus@25 Deg.C	GPa	15.1	13	22.1	18	13
CTE	ppm	40	30	18	51	30
Product Benefit		1.Good Reliability 2.Long open time	1.For printing & dispensing 2.Chemical resistance	1.Extreme high TC 2.Great adhesion on Ag & Au finish	1.Long open time 2.Low volume resistance 3.Die size up to 5*5	1.Good RBO 2.Die size up to 5*5 3.Good adhesion on Cu